

# SOT162-1

plastic small outline package; 16 leads; body width 7.5 mm

8 February 2016

Package information

## 1. Package summary

|                                       |                     |
|---------------------------------------|---------------------|
| <b>Terminal position code</b>         | D (double)          |
| <b>Package type descriptive code</b>  | SO16                |
| <b>Package type industry code</b>     | SO16                |
| <b>Package style descriptive code</b> | SO (small outline)  |
| <b>Package style suffix code</b>      | NA (not applicable) |
| <b>Package body material type</b>     | P (plastic)         |
| <b>IEC package outline code</b>       | 075E03              |
| <b>JEDEC package outline code</b>     | MS-013              |
| <b>Mounting method type</b>           | S (surface mount)   |
| <b>Issue date</b>                     | 19-2-2003           |

Table 1. Package summary

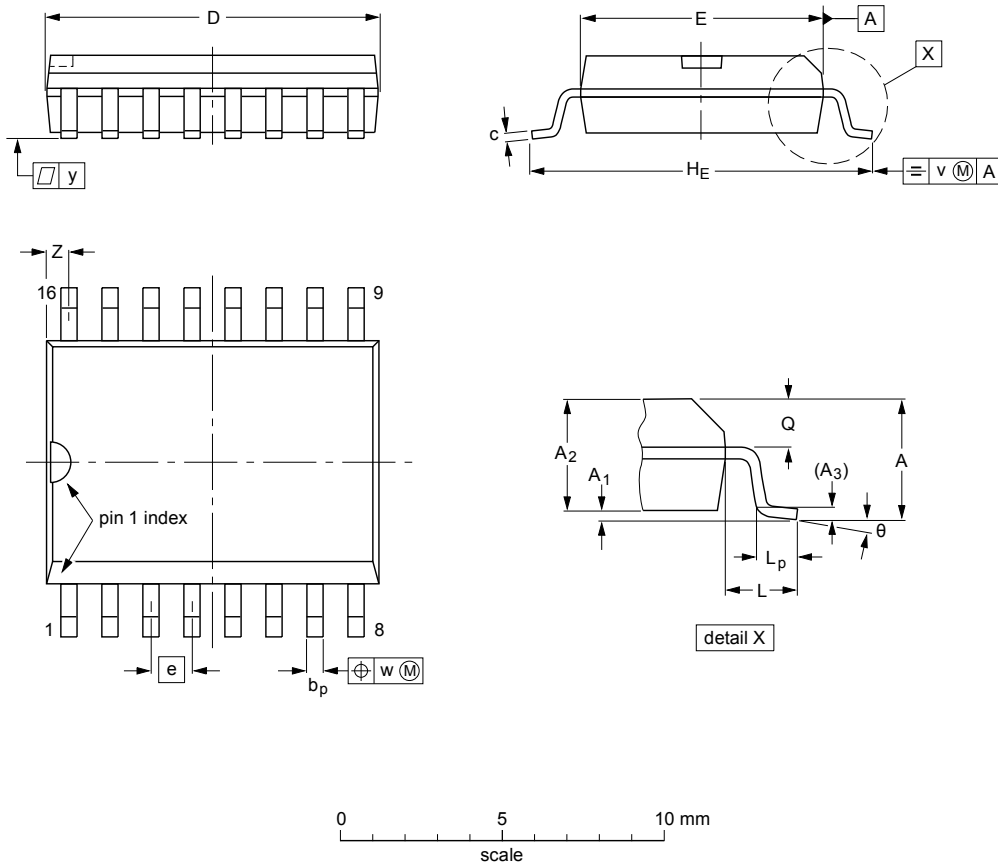
| Symbol         | Parameter                      | Min   | Typ | Nom  | Max  | Unit |
|----------------|--------------------------------|-------|-----|------|------|------|
| D              | package length                 | 10.1  | -   | 10.2 | 10.5 | mm   |
| E              | package width                  | 7.4   | -   | 7.5  | 7.6  | mm   |
| A              | seated height                  | [tbd] | -   | 2.65 | 2.65 | mm   |
| A <sub>2</sub> | package height                 | 2.25  | -   | 2.35 | 2.45 | mm   |
| n <sub>2</sub> | actual quantity of termination | -     | -   | 16   | -    |      |



2. Package outline

SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

| UNIT   | A max. | A <sub>1</sub> | A <sub>2</sub> | A <sub>3</sub> | b <sub>p</sub> | c              | D <sup>(1)</sup> | E <sup>(1)</sup> | e    | H <sub>E</sub> | L     | L <sub>p</sub> | Q              | v    | w    | y     | Z <sup>(1)</sup> | θ        |
|--------|--------|----------------|----------------|----------------|----------------|----------------|------------------|------------------|------|----------------|-------|----------------|----------------|------|------|-------|------------------|----------|
| mm     | 2.65   | 0.3<br>0.1     | 2.45<br>2.25   | 0.25           | 0.49<br>0.36   | 0.32<br>0.23   | 10.5<br>10.1     | 7.6<br>7.4       | 1.27 | 10.65<br>10.00 | 1.4   | 1.1<br>0.4     | 1.1<br>1.0     | 0.25 | 0.25 | 0.1   | 0.9<br>0.4       | 8°<br>0° |
| inches | 0.1    | 0.012<br>0.004 | 0.096<br>0.089 | 0.01           | 0.019<br>0.014 | 0.013<br>0.009 | 0.41<br>0.40     | 0.30<br>0.29     | 0.05 | 0.419<br>0.394 | 0.055 | 0.043<br>0.016 | 0.043<br>0.039 | 0.01 | 0.01 | 0.004 | 0.035<br>0.016   |          |

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

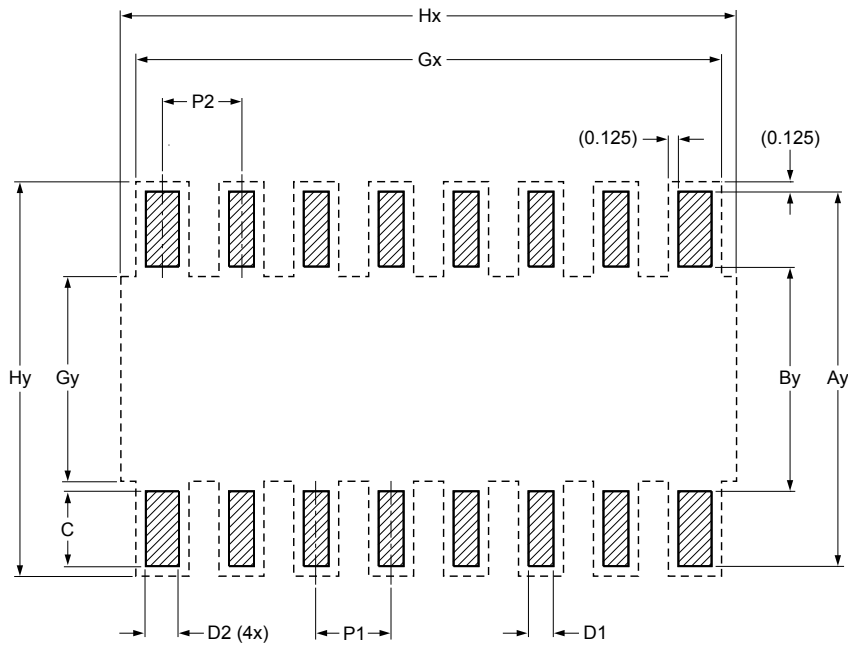
| OUTLINE VERSION | REFERENCES |        |       |  | EUROPEAN PROJECTION | ISSUE DATE           |
|-----------------|------------|--------|-------|--|---------------------|----------------------|
|                 | IEC        | JEDEC  | JEITA |  |                     |                      |
| SOT162-1        | 075E03     | MS-013 |       |  |                     | 99-12-27<br>03-02-19 |

Fig. 1. Package outline SO16 (SOT162-1)


### 3. Soldering

Footprint information for reflow soldering of SO16 package

SOT162-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 - - - - occupied area

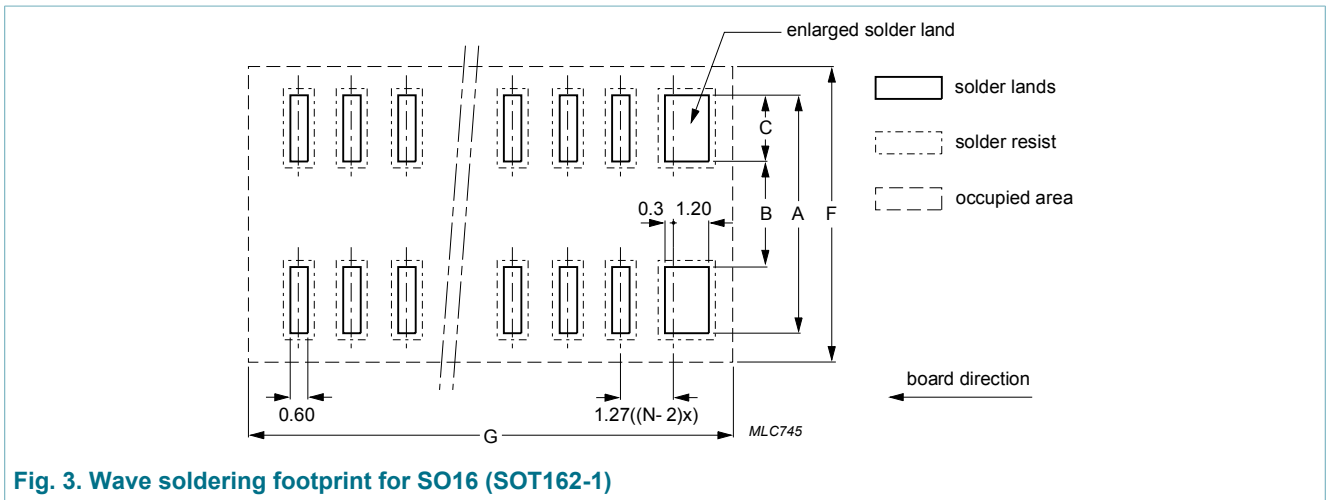
DIMENSIONS in mm

| P1    | P2    | Ay     | By    | C     | D1    | D2    | Gx     | Gy    | Hx     | Hy     |
|-------|-------|--------|-------|-------|-------|-------|--------|-------|--------|--------|
| 1.270 | 1.320 | 11.200 | 6.400 | 2.400 | 0.700 | 0.800 | 10.040 | 8.600 | 11.900 | 11.450 |

so162-1\_fr

Fig. 2. Reflow soldering footprint for SO16 (SOT162-1)

plastic small outline package; 16 leads; body width 7.5 mm



## 4. Legal information

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## 5. Contents

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|                           |   |
|---------------------------|---|
| 1. Package summary.....   | 1 |
| 2. Package outline.....   | 2 |
| 3. Soldering.....         | 3 |
| 4. Legal information..... | 5 |

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